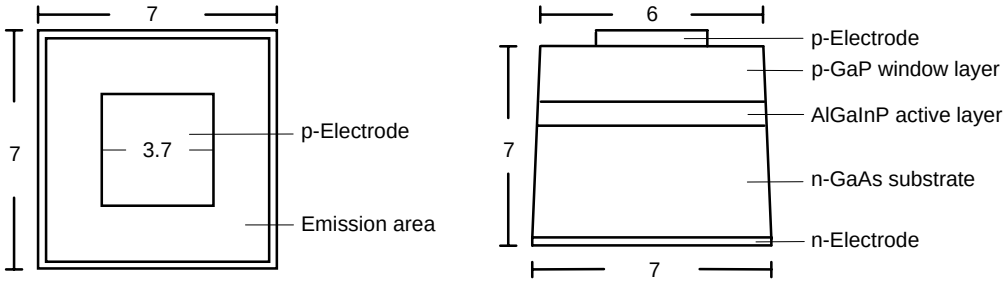
■ Features :

- HP MOVPE epi wafer
- Low VF and superior thermal stability
- Good for low current applications
- High light output at four sides results high total light output and good Brightness uniformity
- Suitable for small and thin package
- High reliability

■ Typical Applications :

- SMD Chip LED
- Dot Matrix
- Display

■ Outline Dimensions : (Unit: mil)



■ Physical Structure :

Chip dimension	Chip size	7.0 mils x 7.0 mils
	Thickness	7.0 mils
	Emission area	6.0 mils
	Bonding pad	3.7 mils
Electrode	Top: P (anode)	Aluminum (Gold optional)
	Backside: N (cathode)	Gold alloy
Surface condition	Not frosted	

■ Electro-Optical Characteristics : (Ta = 25℃)

Parameter	Symbol		Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F		I_F = 20 mA	-	1.90	2.30	V
Reverse Voltage	V_R		I_R = 10 μA	5	-	-	V
Wavelength	λ_D		I_F = 20 mA	-	626	-	nm
	Hue			616	623	631	
Spectral width at half height	$\triangle\lambda$		I_F = 20 mA	-	18	-	nm
Luminous Intensity	I_V	B	I_F = 20 mA	20	-	-	mcd
		C		30	-	-	
		D		40	-	-	

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■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

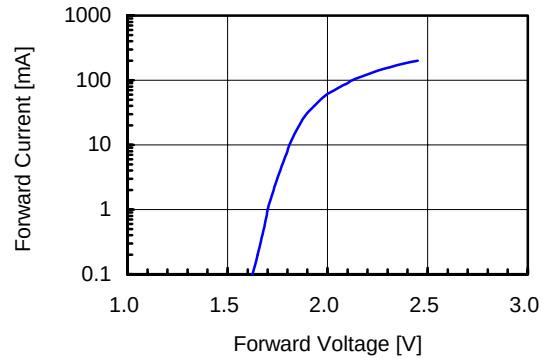


Fig 2. Relative Intensity vs. Forward Current

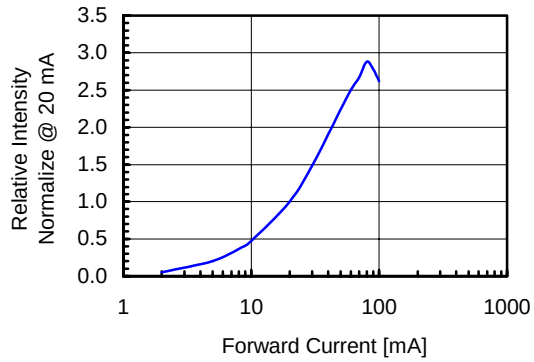


Fig 3. Forward Voltage vs. Temperature

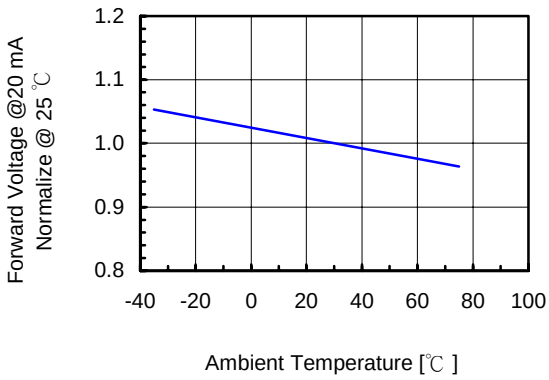


Fig 4. Relative Intensity vs. Temperature

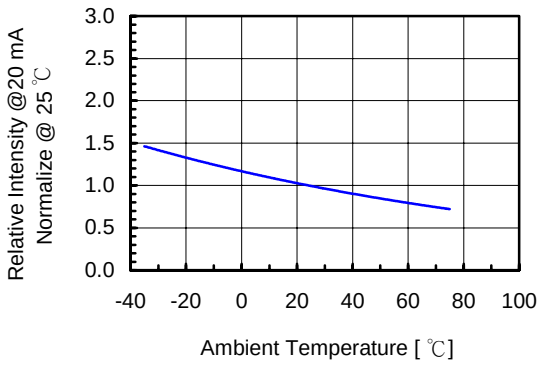
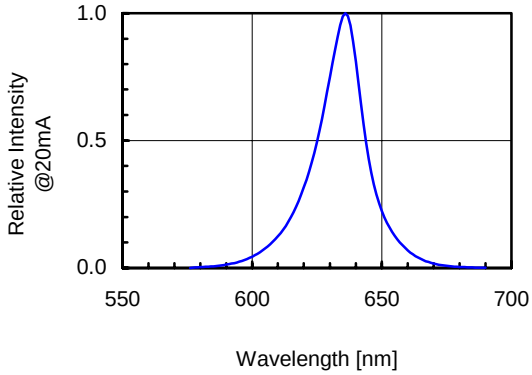


Fig 5. Relative Intensity vs. Wavelength



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